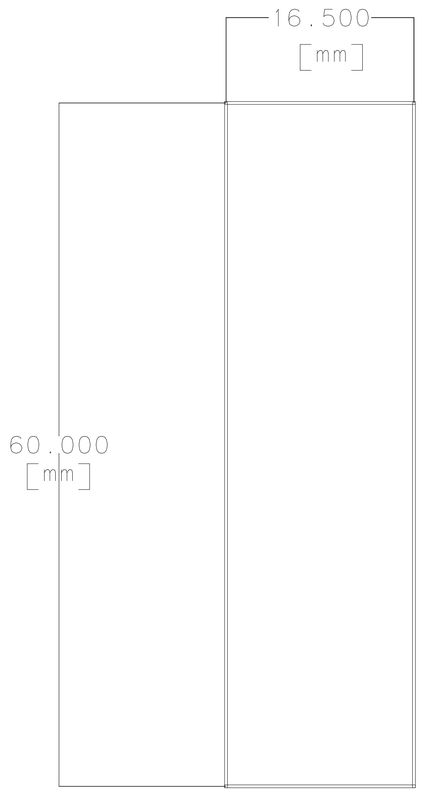

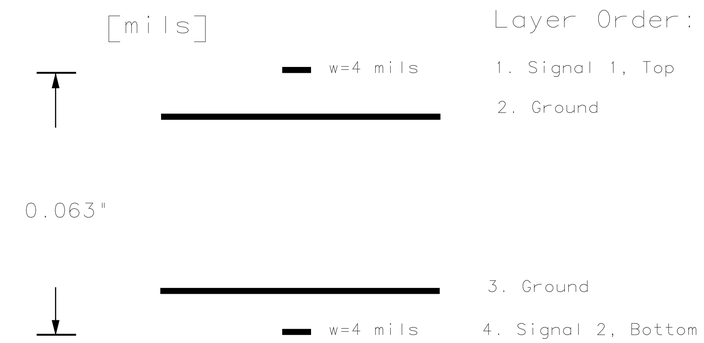

Board Characteristics: 4-Layer Board Impedance control

0. All dimension in mm unless specified otherwise.
1. Material: FR4
2. Board Thickness: 0.063"
3. Minimum Trace Width/Crearance 0.004"
4. 1 oz Copper for top, bottom and power layers
5. Electroless Nickel/Immersion Gold plating; apply solder mask.
   min 25 um Cu, 2.5-5 um Ni, 0.05-0.2 um Au (Electroless Ni/Immersion Au).
6. Silkscreen on Both Sides

8. FHS tolerances : +/- 0.05mm (0.002")
9. Trace Impedance 50 Ohm
10. This is a pressfit tech. thru hole with the following specs:
    - Diameter of drilled hole: 0.7mm +/-0.02mm
    - Diameter of finished plated through hole: 0.6 mm +/-0.05mm
    - Hole Plating: min 25 um Cu, 2.5-5 um Ni, 0.05-0.2 um Au (Electroless Ni/Immersion Au).

BOARD's HOLE SCHEDULE

FHS	COUNT	PLATED	COMMENT
.0236	180	YES	Note 10

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
FRACTIONS DECIMALS .008 ANGLES
DO NOT SCALE DRAWING

TREATMENT

FINISH

SIMILAR TO | ACT. WT | CALC WT

CONTRACT NO.

APPROVALS		DATE
DRAWN	M. Bogdan	9/13/13
CHECKED	M. Bogdan	9/13/13
ISSUED		

THE UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE FTK P3 Test Card Specification Drawing

SIZE | FSCM NO. | DWG. NO. 2788 | REV. B

SCALE 1/2 | SHEET 1 of 1

THIS SHEET IS COMPUTER GENERATED